

EAST - text search

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L29	11	(US-20010017410-\$).did. or (US-5196725-\$ or US-6097081-\$ or US-6175149-\$ or US-6313520-\$ or US-6319753-\$ or US-6424031-\$ or US-6229202-\$ or US-6008073-\$).did. or (JP-06125021-\$ or JP-62117355-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 16:16
L28	1	257/123.ccls. and (gull or j or wing or winged or bent) near2 (lead)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 16:01
L27	1339	438/123.ccls.	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 16:00
L26	255	438/117.ccls.	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 16:00
L9	318	257/692.ccls. and (gull or j or wing or winged or bent) near2 (lead)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 16:00
L20	420	438/111.ccls.	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:46
L25	190	(leadframe or lead near frame) and (loc or lead-on-chip or (lead or paddle) near2 (over or upon or above or top or overlying) near2 (chip or die)) same (wirebond\$4 or bond\$4 near wire) and (package or device or leadframe or lead near frame) near6 (height or profile)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:29
L24	507	(leadframe or lead near frame) and (loc or lead-on-chip or (lead or paddle) near2 (over or upon or above or top or overlying) near2 (chip or die)) same (wirebond\$4 or bond\$4 near wire) and (lead or terminal or pins) near4 (gull or gulled or j or l or bent or curved or folded or folding or bending)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:28
L21	1285	(leadframe or lead near frame) and (loc or lead-on-chip or (lead or paddle) near2 (over or upon or above or top or overlying) near2 (chip or die)) same (wirebond\$4 or bond\$4 near wire)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:26

L19	139	(die or chip) near4 (paddle or (attach\$4 or mount\$4) near2 (pad or area or region)) near10 (lead or leadframe or lead near frame) near10 (bottom or under or underneath or lower or below or downside) and (wire near bond\$4 or wirebond\$4) near8 (lead or leadframe or lead near frame or pad or paddle) near10 (bottom or under or underneath or lower or below or downside)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:24
L15	996	257/696.ccls.	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:22
L16	324	257/696.ccls. and (gull or j or wing or winged or bent) near2 (lead)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:05
L14	5091	(die or chip) near4 (pad or paddle or (attach\$4 or mount\$4) near2 (area or region)) near10 (lead or leadframe or lead near frame) and (chip or die) near4 (bottom or under or underneath or lower or below or downside)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:05
L13	179	257/695.ccls.	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 15:05
L10	209	257/694.ccls.	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 14:55
L12	8	(lead) near4 (gull or j! or bent or curved or bending or reverse-gull or !!) and (chip or die) near10 (feet) same (wire near bond\$3 or wirebond\$3)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 14:54
L5	110	(leadframe or lead adj frame) and (profile or height) and (wire near bond\$3 or wirebond\$4) and (lead) near4 (gull or j or bent or curved or bending or reverse-gull) and (chip or die) near6 (below or beneath or under or underneath or lower or bottom) near8 (attach or attaching or paddle)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 14:49
L2	358	257/672.ccls.	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 14:42
L7	161	257/690.ccls. and (gull or j or wing or winged or bent) near2 (lead)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 14:25
L3	381	257/676.ccls. and (gull or j or wing or winged or bent) near2 (lead)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 14:16

L4	474	(leadframe or lead adj frame) and (profile or height) and (wire near bond\$3 or wirebond\$4) and (chip or die) near6 (below or beneath or under or underneath or lower or bottom) near8 (attach or attaching or paddle)	US-PGPUB; USPAT; JPO	OR	ON	2006/02/15 14:15
L1	195	(lead near frame or leadframe) and gull near wing and (wirebond or wirebonding or wire near bond or wire near bonding) and (loc or lead adj chip or lead-on-chip or lead-over-chip or (lead or diepad) near3 (over or above or below or beneath or under or lower or underneath or top) near3 (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 13:14
S27	336	(lead-on-chip or lead adj chip) and (lead) near4 (foot or end or distal or outer or outside) near5 (gull or j or wing or bent or bending or folded or acute) and (wirebond or wire near bond or wire near bonding or wirebonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:21
S26	196	(lead near frame or leadframe) same lead near2 (feet or distal or tie or end or digits or outer or outside) near4 (bent or bending or fold or folded or folding or curved or curving or angled or angle or angling or under or underneath or below or beneath) same (wirebond or wire near bond or wire near bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:03
S25	166	(package or leadframe or lead adj frame or housing) same (lead) near4 (bent or angle or angled) near6 (recess or recessed or under or underneath or below or beneath or folded or lower or folding) near5 (package or housing or base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 10:51
S24	139	(package or leadframe or lead adj frame or housing) same (lead near foot or gull near wing or j near lead) same (profile or height)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 10:39
S23	94	(lead near frame or leadframe) near8 (profile or height) near2 (reduced or reducing or minimized or low or short or small or minimal or minimum or decreased or decreasing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 10:30